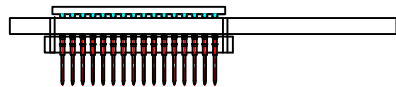
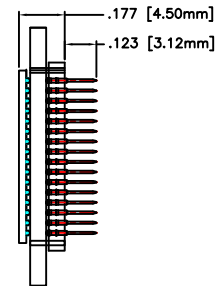
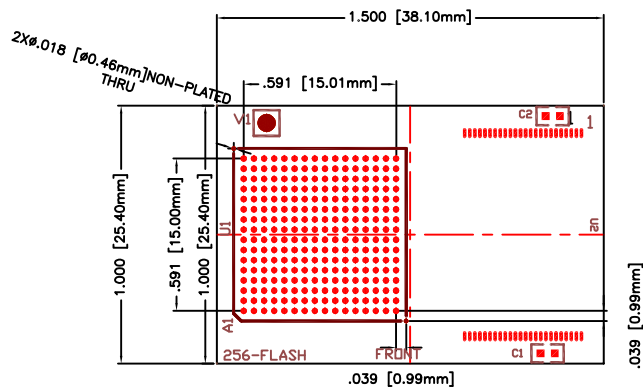


PIN SPECIFICATIONS:
 MATERIAL: BRASS ALLOY 360 1/2 HARD PER QQ-B-628
 FINISH: 10u GOLD OVER 100u NICKEL MIL-C-45204
 ELECTRICAL PERFORMANCE TESTS IAW MIL-STD-202 OR 1344 METHODS:
 MAX VOLTAGE: 50 VAC/60 VDC
 MAX CURRENT: 1 AMP
 CONTACT RES: 010 MAX .01 AMPS/2VDC
 INSULATION RESISTANCE: @500 VDC: 5000 MEGOHMS MIN.
 CAPACITANCE: 1pf MAX.
 SELF INDUCTANCE: 2nH MAX.

MATERIAL SPECIFICATIONS:
 STANDARD MATERIAL:
 GLASS EPOXY FR-4, IPC-4101/24,
 MIL-S-13949/04-GF/GRUL
 94V-0, CONTINUOUS USE TEMP 150C,
 HEAT DEFLECTION TEMP(@264 PSI)175C

REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
---	A	PRELIMINARY	09/30/09	

TOP VIEW



BILL OF MATERIALS		
256-FLASH	PCB QTY 1	
256-CHIP	BGA CHIP QTY 1	SOLDERS TO U1
LHS256-1611-SP	LGA HEADER QTY1	SOLDERS TO U2 BOTTOM SIDE

NOTES:
 BGA DEVICE PROVIDED BY CUSTOMER.
 SOLDER 256 BGA DEVICE TO TOP SIDE OF PCB.
 SOLDER LHS256-1611-SP TO BOTTOM SIDE OF PCB.

PACKAGE:
 SECURE PINS IN DRILLED CARRIER FOR PROTECTION.
 PARTS SHOULD BE PLACED IN BLACK ANTI STATIC BAGS.

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256 BGA INTERPOSER
 WITH PADS FOR EXTERNAL FLASH.

DRAWN BY: ANDREW MONTOYA	SIZE	FSCM NO.	DWG NO. CA256-FLASH	REV A
CHECKED: MIKE OIEM	SCALE 2:1	DATE 09/30/09	SHEET	